

ABSTRACT

A highly reliable bonding process is provided. The wire bonding method includes: (a) bonding a tip portion of a wire to a first electrode by pressing an open end section of a first hole of a first tool against the tip portion of the wire that is passed through the first hole and protrudes outside the first hole, and (b) bonding a part of a section of the wire that is lead out from the first electrode to a second electrode. The first tool is passed through a second hole of a second tool. The width of an open end section of the second hole is formed greater than the width of the open end section of the first hole. The step (b) is conducted by pressing the open end section of the second hole against the part of the wire.